

SKiM<sup>®</sup> 5

## IGBT Modules

### SKiM 270GD176D

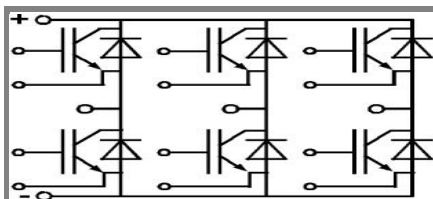
Target Data

#### Features

- Homogenous Si
- Trench = Trenchgate Technology
- $V_{CEsat}$  with positive temperature coefficient
- High short circuit capability, self limiting to  $6x I_C$

#### Typical Applications

- AC inverter drives mains 575 - 750 V AC
- public transport (auxiliary syst.)

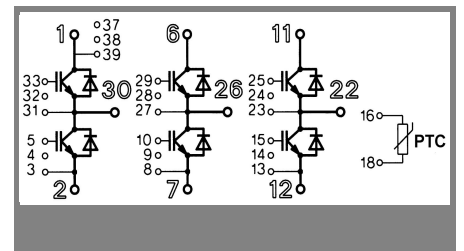
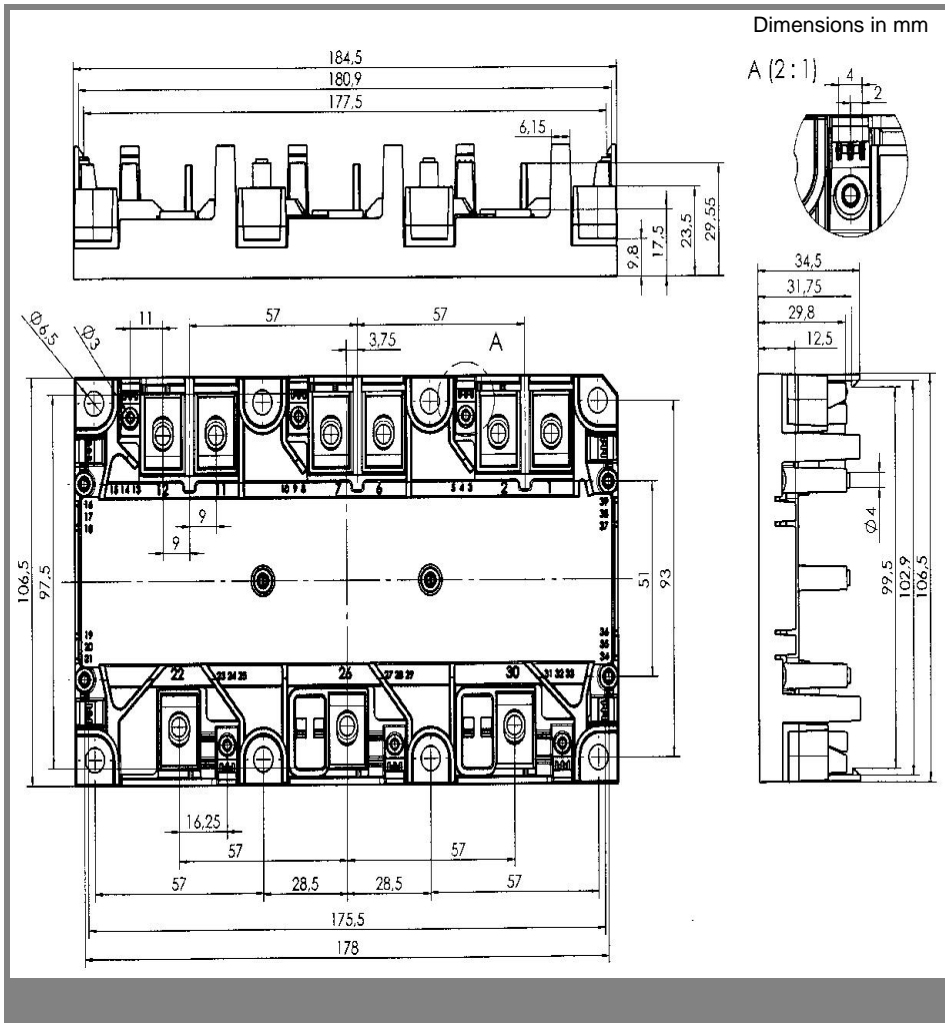


GD

Absolute Maximum Ratings		$T_{case} = 25^\circ\text{C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
<b>IGBT</b>			
$V_{CES}$		1700	V
$I_C$	$T_h = 25 (70)^\circ\text{C}$	270 (200)	A
$I_{CM}$	$T_h = 25 (70)^\circ\text{C}$ , $t_p = 1 \text{ ms}$	540 (400)	A
$V_{GES}$		$\pm 20$	V
$T_j (T_{stg})$	$T_{OPERATION} \leq T_{stg}$	-40 ... 125	$^\circ\text{C}$
$V_{isol}$	AC, 1 min.	4000	V
<b>Inverse diode</b>			
$I_F = -I_C$	$T_h = 25 (70)^\circ\text{C}$	215 (155)	A
$I_{FM} = -I_{CM}$	$T_h = 25 (70)^\circ\text{C}$ , $t_p < 1 \text{ ms}$	540 (400)	A
$I_{FSM}$	$t_p = 10 \text{ ms}$ ; sin.; $T_j = 150^\circ\text{C}$	2200	A

Characteristics		$T_{case} = 25^\circ\text{C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>IGBT</b>					
$V_{GE(th)}$	$V_{GE} = V_{CE}$ ; $I_C = \text{mA}$	5,2	5,8	6,4	V
$I_{CES}$	$V_{GE} = 0$ ; $V_{CE} = V_{CES}$ ; $T_j = 25 (125)^\circ\text{C}$				mA
$V_{CEO}$	$V_{GE} = 0 \text{ V}$ ; $T_j = 25 (125)^\circ\text{C}$		1 (0,9)	1,2 (1,1)	V
$r_{CE}$	$V_{GE} = 0 \text{ V}$ ; $T_j = 25 (125)^\circ\text{C}$		3,3 (5)	4,2	m $\Omega$
$V_{CEsat}$	$I_C = 300 \text{ A}$ ; $V_{GE} = 15 \text{ V}$ ; $T_j = 25 (125)^\circ\text{C}$ on chip level		2 (2,4)	2,45	V
$C_{ies}$	$V_{GE} = ; V_{CE} = \text{V}$ ; $f = \text{MHz}$				nF
$C_{oes}$	$V_{GE} = ; V_{CE} = \text{V}$ ; $f = \text{MHz}$				nF
$C_{res}$	$V_{GE} = ; V_{CE} = \text{V}$ ; $f = \text{MHz}$				nF
$L_{CE}$	$T_c = 25^\circ\text{C}$			20	nH
$R_{CC'+EE'}$			0,9 (1,1)		m $\Omega$
$t_{d(on)}$	$V_{CC} = 1200 \text{ V}$				ns
$t_r$	$I_C = 300 \text{ A}$				ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 8 \Omega$				ns
$t_f$	$T_j = 125^\circ\text{C}$				ns
$E_{on} (E_{off})$	$V_{GE} \pm 15 \text{ V}$		180 (120)		mJ
<b>Inverse diode</b>					
$V_F = V_{EC}$	$I_F = 300 \text{ A}$ ; $V_{GE} = 15 \text{ V}$ ; $T_j = 25 (125)^\circ\text{C}$				V
$V_{TO}$	$T_j = ^\circ\text{C}$				V
$r_T$	$T_j = ^\circ\text{C}$				V
$I_{RRM}$	$I_F = \text{A}$ ; $T_j = ^\circ\text{C}$				A
$Q_{rr}$	$V_{GE} = \text{V di/dt} = \text{A}/\mu\text{s}$				$\mu\text{C}$
$E_{rr}$	$R_{Gon} = R_{Goff} =$				mJ
<b>Thermal characteristics</b>					
$R_{thjh}$	per IGBT			0,175	K/W
$R_{thjh}$	per FWD			0,29	K/W
<b>Temperature Sensor</b>					
$R_{TS}$	$T = ^\circ\text{C}$		1 (1,67)		k $\Omega$
tolerance	$T = ^\circ\text{C}$		3 (2)		%
<b>Mechanical data</b>					
$M_1$	to heatsink (M5)	2		3	Nm
$M_2$	for terminals (M6)	4		5	Nm
w				460	g

# SKiM 270GD176D ...



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.